



**In the United States Patent and Trademark Office**

Serial Number: 10/760246  
Application. Filed: January 21, 2004  
Applicant: Kia Silverbrook; Norman Micheal Berry; Garry Raymond Jackson; Akira Nakazawa  
Application Title: Printhead Assembly with Interconnected Printhead Modules  
Examiner/GAU: Laura E Martin 2853  
Dated December 7, 2006  
At: Balmain, NSW  
Docket No. MPA10US

**REPLY**

Commissioner for Patents  
Washington, District of Columbia 20231

Dear Sir:

In response to the Advisory Action of November 27, 2006, Applicant encloses a Request for Continuing Examination together with the prescribed fee.

The supporting submissions are set out below.

Applicant submits that the enclosed RCE fully complies with 37 CFR 1.114 and therefore asks that the finality of the last report be withdrawn and the submissions of May 11, 2004 be fully considered.

**SUBMISSIONS**

**35 U.S.C. §102 - Claims 1 and 5**

Claims 1 and 5 stand rejected for lack of novelty in light of US 6,439,908 to Silverbrook.

Claim 1 requires that the printhead integrated circuits (IC's) are **fixably** mounted to the support member. The Examiner has read the molding 32 of '908 onto the support member of the present invention. However, the '908 disclosure is primarily directed to an assembly where the printhead modules 12 (and therefore the printhead IC's 18) are removable and replaceable. In the present invention the printhead IC's on each module are all fixedly mounted to a single support member.